PAL Accelerator/Vacuum Technology and EIC

Taekyun Ha

Pohang Accelerator Laboratory, Republic of Korea





Outline

- Status of PLS-II and PAL-XFEL
- Vacuum R&D in PAL
 - ✓ Vacuum System for a 4th Generation Storage Ring Studied in PAL
 - ✓ 3D Printing Techniques to the Vacuum System
 - ✓ Improvement of Vacuum Property of materials
- Summary

PLS-II Overview: Chronology

I. PLS

Project started	Apr.	1988
-----------------------------------	------	------

User service startedSep. 1995

II. Major Upgrade of the PLS (PLS-II)

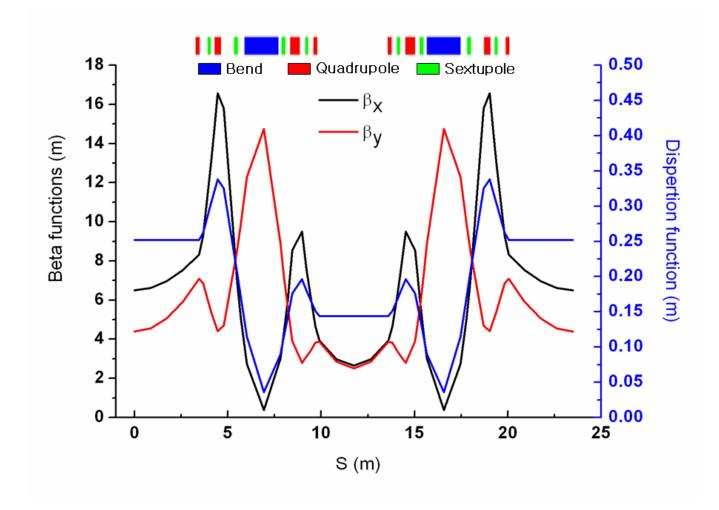
3.0 GeV PLS-II Upgrade begin	Jan.	2009
	• • • • • • • • • • • • • • • • • • • •	

■ 3.0 GeV PLS-II Upgrade Complete Dec. 2011

User service startedMar. 2012

■ 3.0 GeV 400 mA Top-up operation July 2015

PLS-II Overview: Storage ring



✓ 42 % of the circumference available for straight sections

Beam Energy 3.0GeV
 Beam Current 400mA
 Lattice DBA
 Superperiods 12
 Emittance 5.8 nm·rad

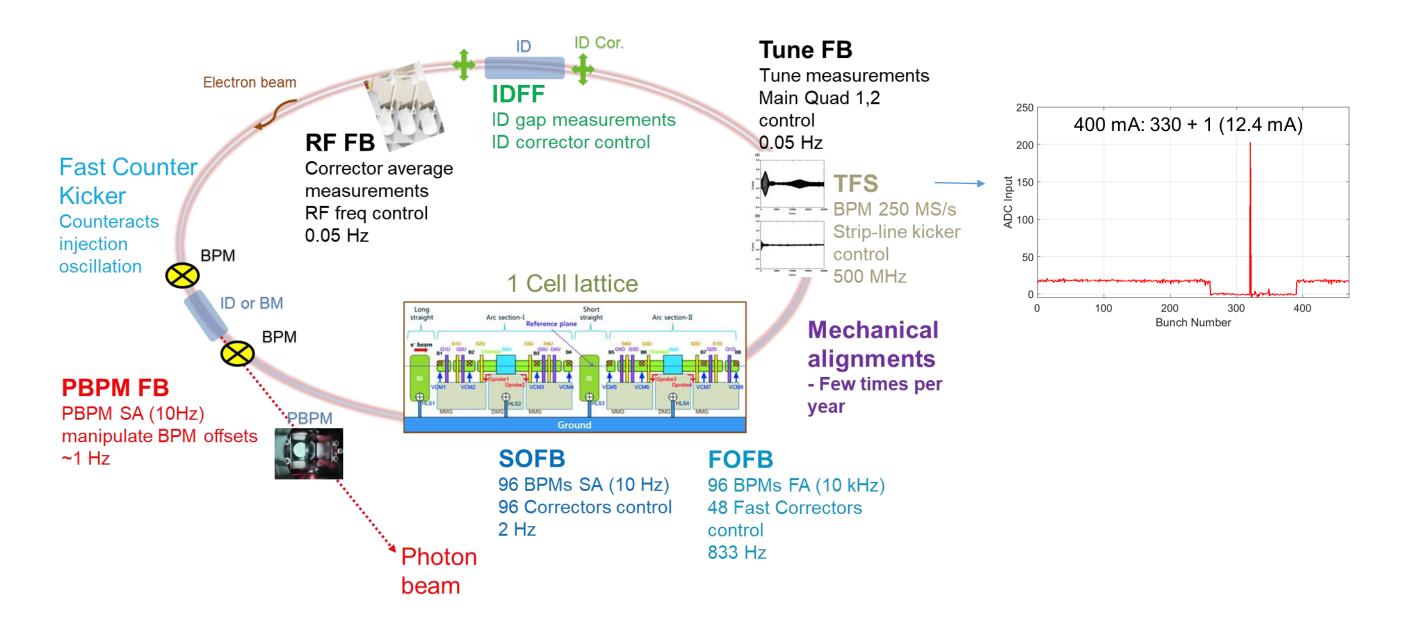
Emittance 5.8 nm·rad
 Tune 15.37 / 9.15
 RF Frequency 499.97 MHz

Circumference 280 m



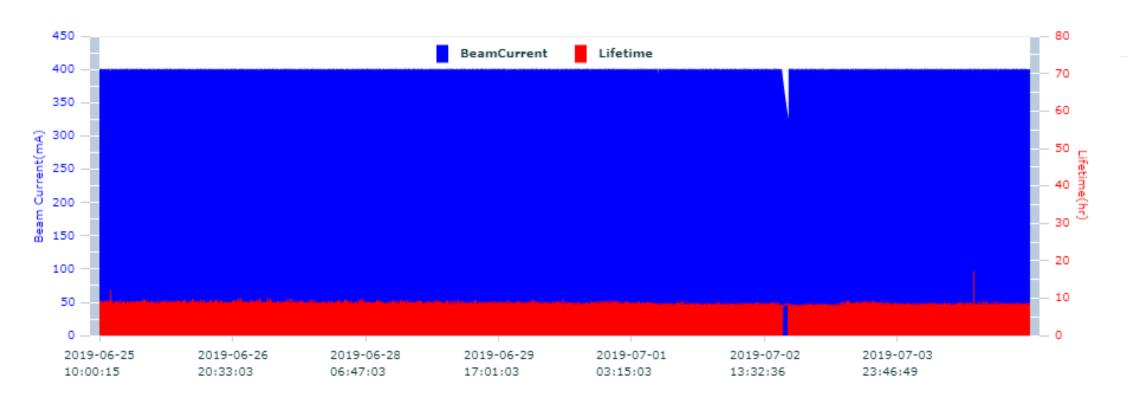


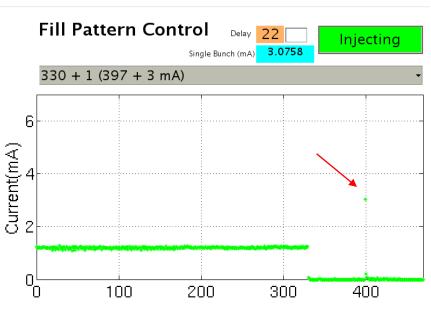
PLS-II Overview: Instrumentations for high performance operation



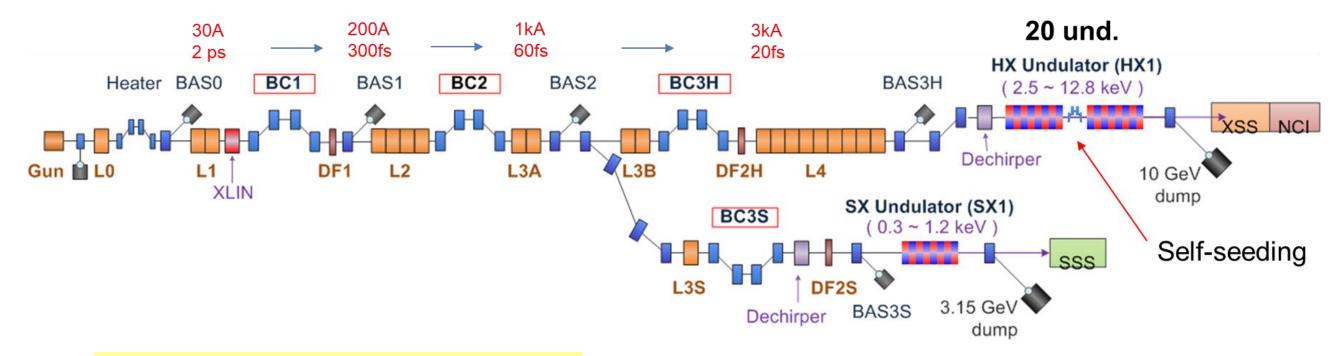
PLS-II Overview: Operation

- 4 user runs (No dump) in the 1st half of 2019
- Routinely 400 mA Top-up (Hybrid mode)
- SRF CM3 leak (Recovery until 2020) → Currently 250 mA Top-up operation





PAL-XFEL Overview



Main	param	eters
------	-------	-------

e⁻ Energy 11 GeV
e⁻ Bunch charge 20-200 pC
Slice emittance < 0.4 mm mrad
Repetition rate 60 Hz
Pulse duration 5 fs – 50 fs
Peak current 3 kA
SX line switching DC magnet
(to be changed to Kicker by 2020)

Undulator Line	HX1	SX1
Photon energy [keV]	2.0 ~ 14.5	0.25 ~ 1.25
Beam Energy [GeV]	4 ~ 11	3.0
Wavelength Tuning	energy	gap
Undulator Type	Planar, out-vac.	Planar
Undulator Period / Gap [mm]	26 / 8.3	35 / 9.0



PAL-XFEL Overview: Brief Time Line

Λ	n r	:	7		1	1
A	pr	Ш	Z	U		ᅩ

■ Sep. 2012

■ Jan. 2015

■ Dec. 2016

April 12, 2016

■ June 14, 2016

• Oct. 28, 2016

■ Nov. 27, 2016

March 16, 2017

■ June 7, 2017

■ May 30, 2018

■ Nov. 2018

■ Mar. 2019

PAL-XFEL project started

Construction started

Building completed

Installation completed

Commissioning started

First SASE lasing at 0.5 nm

Lasing at 0.15 nm

Saturation of 0.15 nm (project completed)

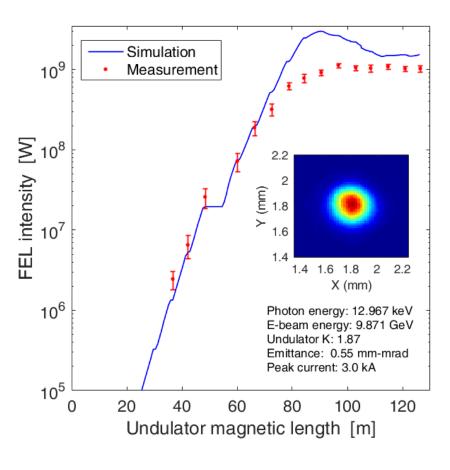
Saturation of 0.1 nm (design goal achieved)

First User Service

Self-Seeding Test

Permission granted to operate up to 11 GeV

60 Hz operation started



PAL-XFEL Overview: FEL Performance

FEL power stability

FEL position stability

■ FEL central wavelength jitter

FEL beam availability

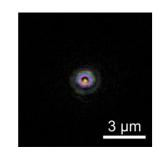
Timing stability

between X-ray pulses and optical pulses

Relative electron beam energy jitter

• Electron beam arrival time jitter

Ptychography (J. Hasting)



Reconstructed object (scan area in orange)

Reconstructed complex illumination at object plane

< 5% RMS

< 10% of beam size

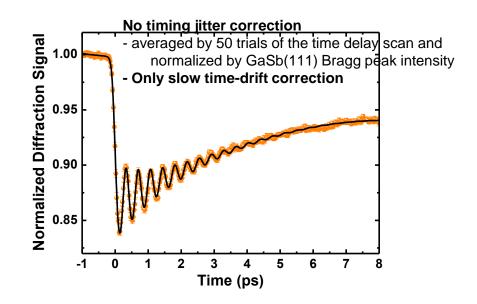
0.024 % (1/5 of SASE BW)

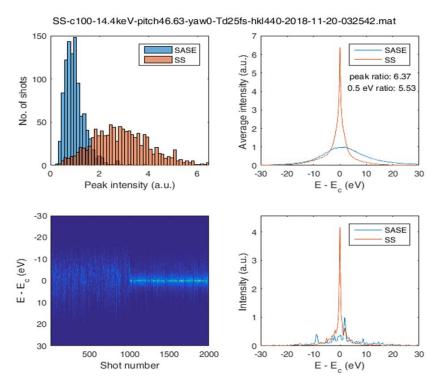
> 96%

18 fs (rms)

1.2 x 10-4

12 fs





Machine components developed in Korea

O Developed in the PLS-II project

- In-vacuum undulator
- MPS
- Many vacuum components
- RF window

O Developed in the PAL-XFEL project

- SLED
- CCPS
- Accelerator column
- RF window
- Magnet
- Undulator
- Klystron

O In the future

- Thyratron
- E-gun
- Capacitor

Photon absorber

- Cold forged OFHC
- High thermal conductivity
- High yield stress



❖ Pill type getter

- Distributed pumping for straight section

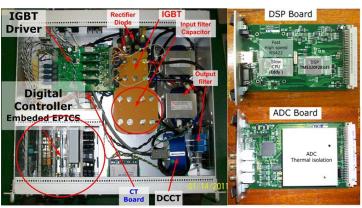


Modulator, CCPS

❖ In-vacuum undulator



❖ MPS



❖ Accelerating column, SLED, RF window

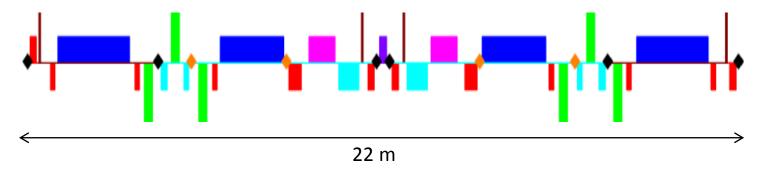


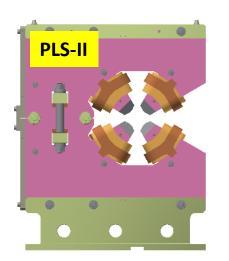
Modern Low Emittance Storage Ring

■ The 3rd Generation Storage Ring Lattice:

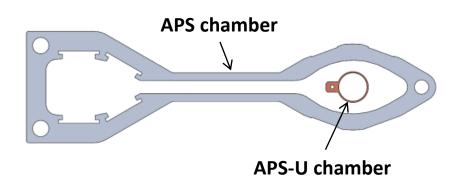


■ The 4th Generation Storage Ring Lattice:





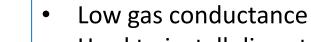




Main features of recent vacuum systems for 4GSR:

Small aperture

Tight space



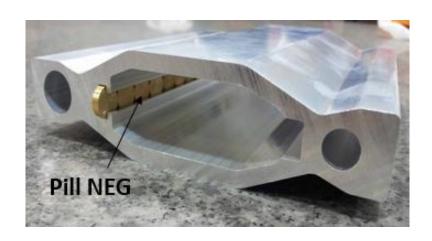
Hard to install discrete vacuum components



"Distributed" pumping and "distributed" photon absorption

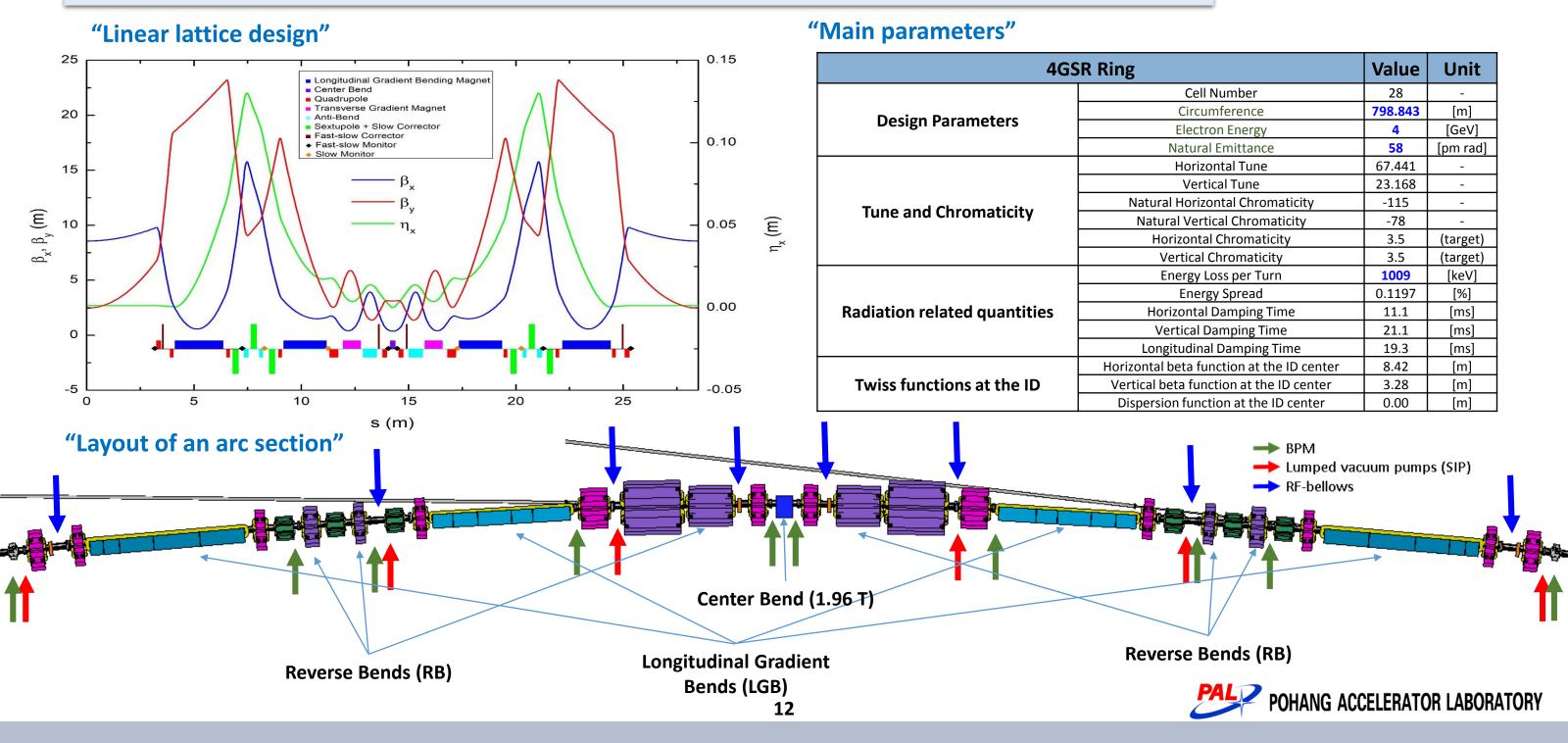
Limitations of the current vacuum techniques for the 4GSR

- * Conventional vacuum chamber with the large antechamber, where the discrete pumps and photon absorbers are installed, will not be suitable to the future advanced lattice as the number of magnets is increasing and as the bore size is decreasing further.
- NEG coated chamber is the best option at the present time but it still needs a lot of time and effort to optimize the coating process for each chamber of different shape.
- * The impedance effect on the beam due to the NEG coated layer has not been fully understood yet.
- → A vacuum chamber using "pill-type" getters with 3D printing techniques is a practical alternative to the conventional vacuum chamber or the NEG coated chamber for the 4GSR.



"Straight section chamber with pill-type getters being in use at PLS-II storage ring"



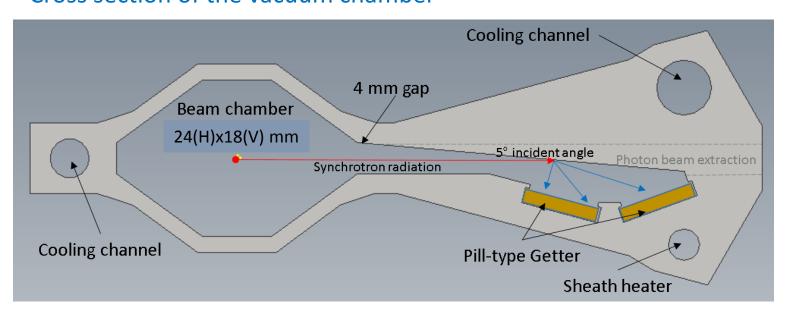


Conceptual design of the vacuum chamber

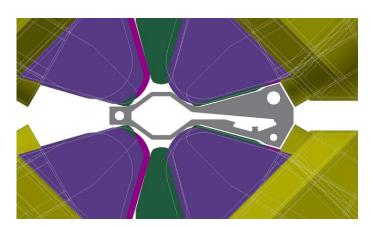
❖ Handling of PSD gases and SR heat loads

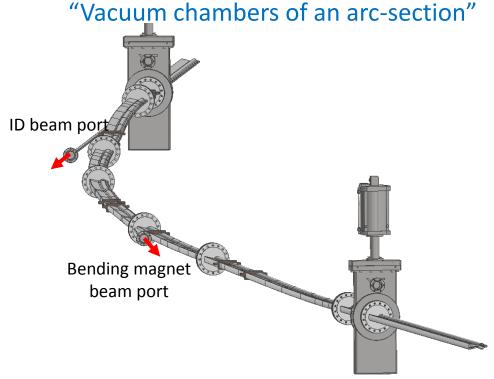
- 1. Aperture of the beam chamber is 24 mm (H) x 18 mm (V).
- 2. 5°-Inclined side chamber wall absorbs most of the photon beams.
- 3. PSD gas is mostly pumped by distributed pill-type getters.
- Cross sections of the vacuum chambers in an arc-section are the same, except for the center-bend chamber which aperture is only 10 mm (V).

"Cross section of the vacuum chamber"



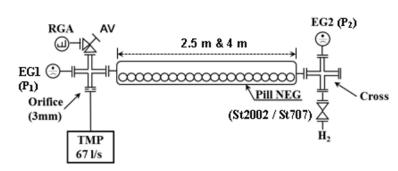
"Vacuum chamber and magnets"





Sticking coefficient of the commercial pill-type getters

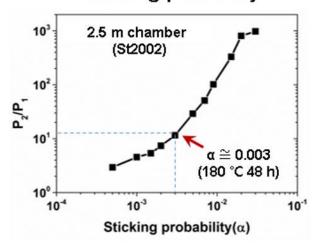
Set up



- The pressure(P₂) is kept constant (1×10-6 mbar) by injecting the H₂ gas
- TMP evacuate the gases that can't be pumped by pill NEG slowly.
- Molflow+ was used for calculation of sticking probability from ratio of pressure.
- > Sticking probability: $\alpha \propto P_2/P_1$

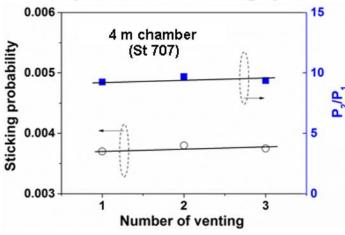
Results of H₂ sorption

Sticking probability



➢ Pill NEG have a value of sticking probability about 0.003 → 1/5 of a NEG coated chamberroughly.

Dependence of venting cycle



 Sticking probability is substantially constant after three additional venting.

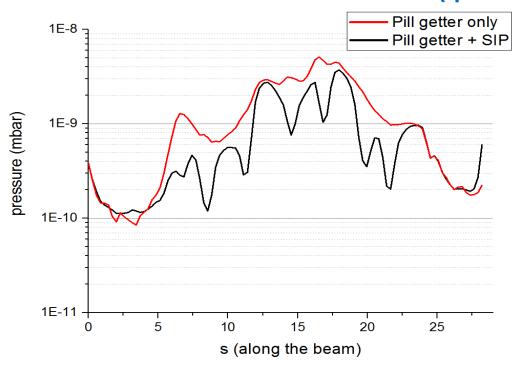
"NEG film vs. Pill-type getter"

Туре	1.2 µm		Note
Facture	Sintering	Compressing	
Activation	200°C, 1 d	180°C, 1 ~ 2 d	
Pumping speed per length	-	Low (< 1/10)	Surf. Area ↓
Sticking probability (α)	0.015 (200°C, 24 h)	0.003 ~ 0.0037 (180°C, 48 h)	
α (after two additional venting)	0.015 → 0.008	Substantially constant	
Capacity (H ₂)	-	1000×	Thickness个
Disadvantages	Aging after venting	Particle	

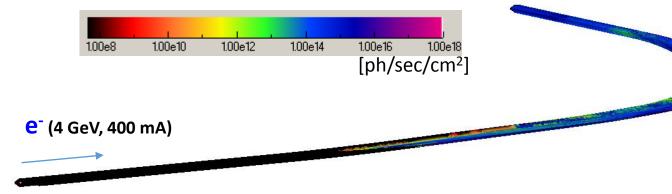
Pressure profile

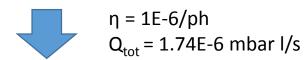
- Total photon stimulated desorption calculated by Synrad is 1.74x10⁻⁶ mbar l/s with PSD coefficient of 1x10⁻⁶ /ph.
- Average pressure with only pill getter pumps of sticking coefficient 0.004 is 1.4x10⁻⁹ mbar and 8x10⁻¹⁰ mbar with additional 8 sputter ion pumps.
- Wire heater is inserted into the side channel of the vacuum chamber for 180°C bake-out and NEG activation.

"H₂ pressure profile of an arc-section after beam dose of more than 1000 Ah ($\eta=1x10^{-6}/ph$)"

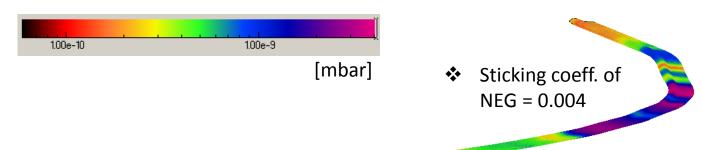


"Synrad simulation (PSD calculation)"





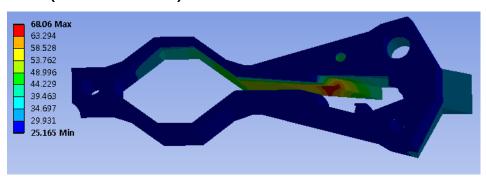
"Molflow simulation (pressure calculation)"





Thermal analysis with the SR heat loads

- Most intense thermal load is 0.77 W/mm² from the center bend.
- Thermal analysis results show that both aluminum and Cu alloy can be used for the vacuum chamber material.
- Aluminum chamber can be fabricated by extrusion, bending and welding.
- Cu alloy chamber can be fabricated by machining of two pieces (top and bottom) and welding.
- Temperature of the sharp edge at a beam exit branch is 68°C (endurable).

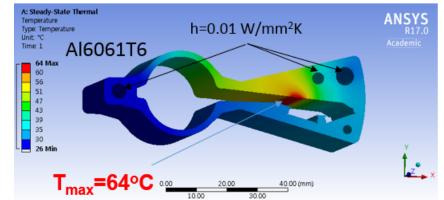


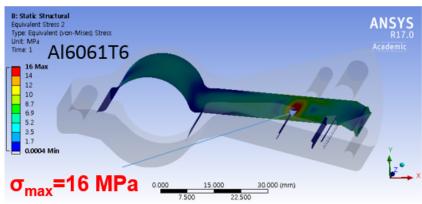
Heat load from Center Bends

	В	Bend angle	Total power	Source distance	Inc_angle (H)	Inc_angle (V)	Foot print V-height	Thermal load
Center bend	1.96 T	1.6°	6 kW	2.25 m	2.35°	5°	0.44 mm	0.77 W/mm ²

Results

Material	T _{max} (chamber)	T _{max} (Water channel)	σ_{max}	σ _{yield} (Cold worked)
Al6061T6	54°C	46°C	16 MPa	214 MPa
OFC Cu (C10100)	48°C	40°C	9 MPa	120 MPa
CuCrZr (C18150)	50°C	41°C	11 MPa	210 MPa





Strengths and weaknesses of the current design

- Easy to fabricate by extrusion where Aluminum alloy can be used
- Extensive R&D to customize NEG coating is not needed
- Moderate activation temperature (180°C) limits the pumping ability of the commercial getter pumps
- Sticking coefficient of the commercial pill-type getter is not high enough

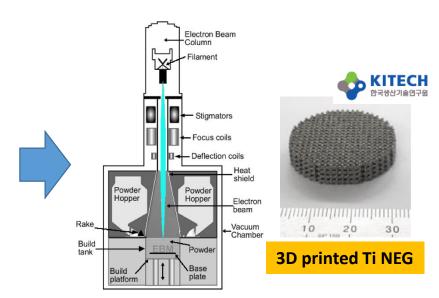
Prototype of a 3D printed getter

- Mesh structure design for maximum specific surface area
- Fabrication of Ti getter using 3D printer with titanium powder in vacuum environment (Electron Beam Melting in vacuum → high purity Ti)
- Pumping speed of one 3D printed Ti getter is measured to be 0.6 l/s, which is as much as 60% that of the conventional NEG
- Alloy (Ti, Zr, V, Al,...) powders are necessary to increase the pumping speed and to lower the activation temperature

"Design of 3D printed getters"

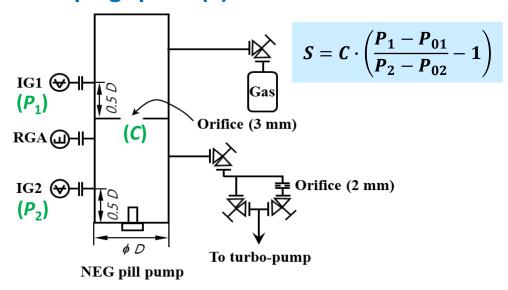
Sampl e	3D CAD design	Diamete r (mm)	Height (mm)	Area (mm²)	Relative Area (%)
Bulk		30	6	1978	100
C2		30	6	4859	246
С3		30	6	6974	353
C4	FUIEE	30	6	9094	460

"3D printing via EBM"

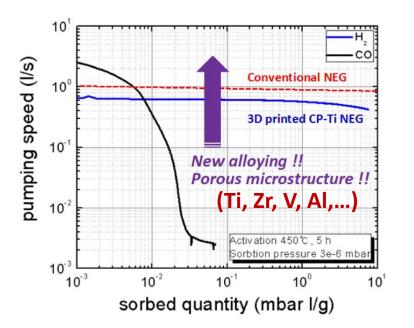


Electron Beam Melting
[image from MPI.com]

"Pumping speed (S) measurement"





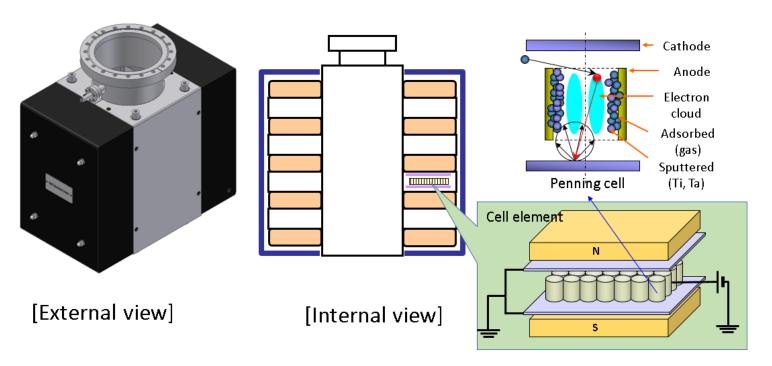




Prototype of a compact 3D printed sputter-ion pump with mesh anode structures

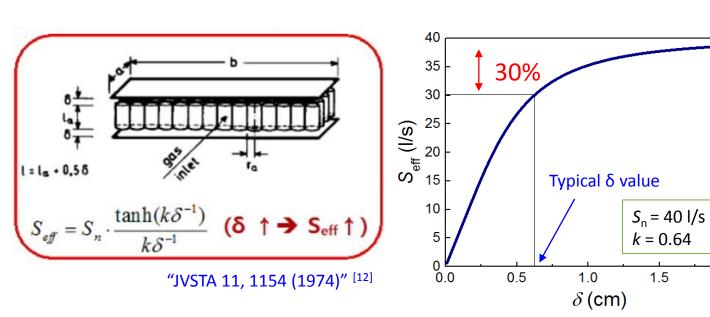
"Pumping mechanism of the sputter-ion pump (SIP)"

- Step 1: Gases enter into electron cloud of a Penning cell by chance
- Step 2: Gases are ionized and incident on the cathodes
- Step 3: Cathode materials (Ti) are sputtered and deposited on the anode surface
- Step 4: Gases incident on the anode combine chemically with the deposited Ti



"Performance gain by optimization of the cell structures"

- Effective pumping speed is limited by the inlet conductance of the cell structure
- Performance optimization of the SIP is a compromise between the $gap(\delta)$ and the anode length(l), and the sum of them is constrained by a required magnetic field
- Transparent anode cell to the gas flow could maximize the inlet conductance if the anode cell could maintain the electron discharge
- Theoretically **30%** improvement is possible → 30% more compact SIP



S_{max}

2.0

Prototype of a compact 3D printed sputter-ion pump with mesh anode structures

"3D printed anode structure for the SIP"

- Mesh anode is proposed for the transparent anode cell structure
- Mesh anode cell by 3D printing via Selective Laser Melting (SLM)
 - ✓ First attempt
 - ✓ Stainless steel powder material
 - ✓ Thickness of 1 mm
 - ✓ Opening area of 50% (not optimized)
 - ✓ Geometric surface of 2,189 cm²
 - ✓ Some manufacturing defects
- Normal anode cell structure fabricated by the same way for reference
 - ✓ Geometrical surface of 1,768 cm²
- Surface area of the mesh anode is 20% higher than the conventional anode



Prototype of a compact 3D printed sputter-ion pump with mesh anode structures

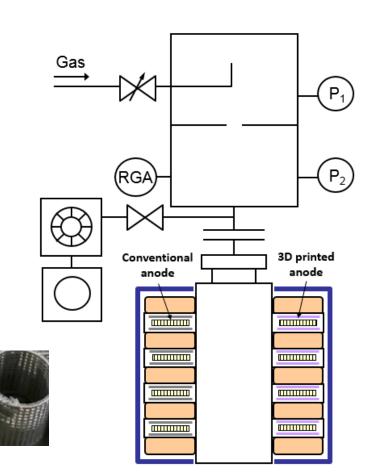
"Pumping speed test (Mesh anode vs. Conventional anode)"

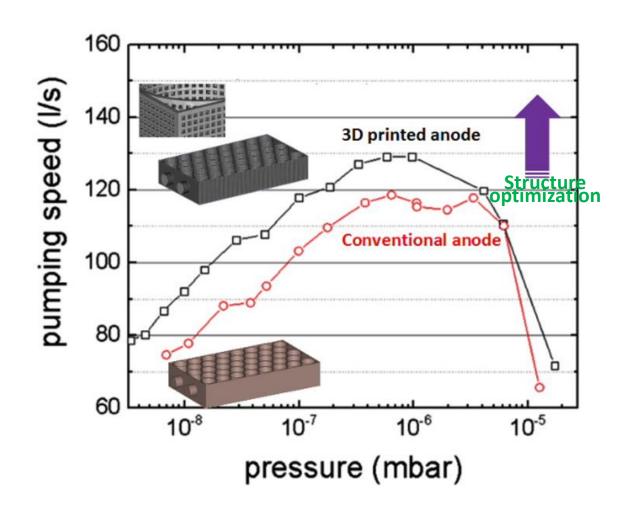
- Prepared a SIP with the mesh anode cell and the conventional anode cell together
- Measured the pumping speed (S) of each type after the same procedure (roughing down, bake-out, saturation, ...)
- Nitrogen gas

$$S = C \cdot \left(\frac{P_1 - P_{01}}{P_2 - P_{02}} - 1\right)$$

"Results"

- 10% higher N₂ pumping speed
 - ✓ Opening area (conductance) is not optimized
 - ✓ Some defects
- → Quantitative analysis of the conductance effect is needed
- → Geometric area effect need to be evaluated







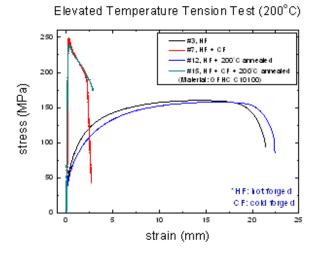
Vacuum Materials

High heat load photon absorber (Cold forged OFHC)

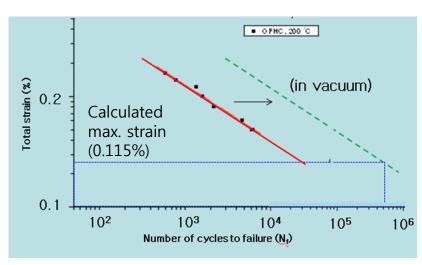
Cold forging vs. Hot forging

- OFHC
 - ✓ High thermal conductivity
 - ✓ E-beam welding
 - ✓ Easily available than Glidcop
- Elevated temperature (200 °C) tension test

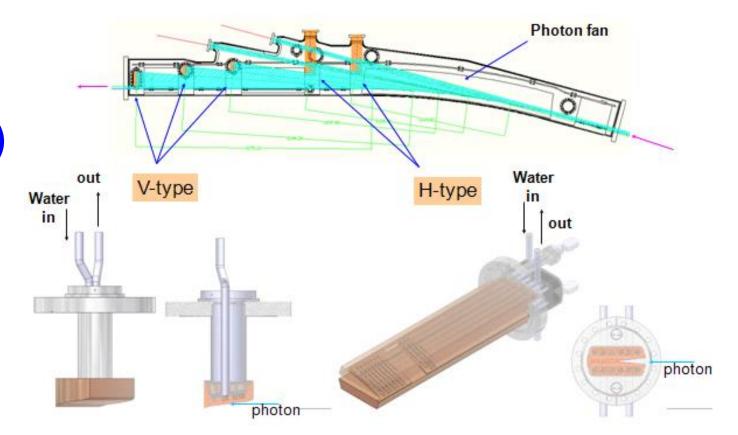
Material process	YS(0.2%) / MPa	TS / MPa	EL/%
Hot forged (OFHC)	48.3	160.3	42.4
Hot + Cold forged	244.4	249.1	5.2
HF + 200°c Annealed	48.9	157.7	43.9
HF + CF + 200℃ Annealed	240.0	240.3	5.8



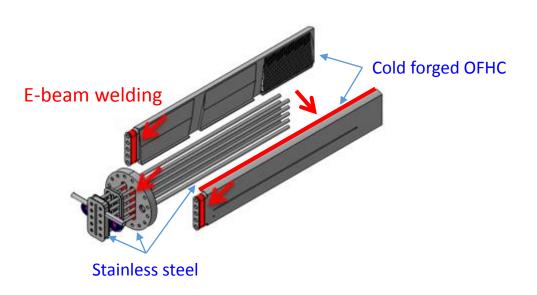
Fatigue lifetime measurement



- Number of cycles to failure for total strain of 0.115 % (most severe point) in air is measured to be larger than 10,000 cycles
- Fatigue lifetime in vacuum is 10 times longer than that in air, typically.
- The lifetime of the PLS-II photon absorber is expected to be longer than 100,000 cycles



Photon absorbers for PLS-II storage ring

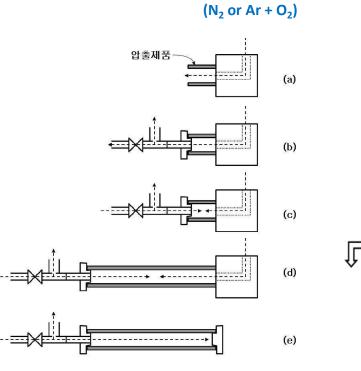


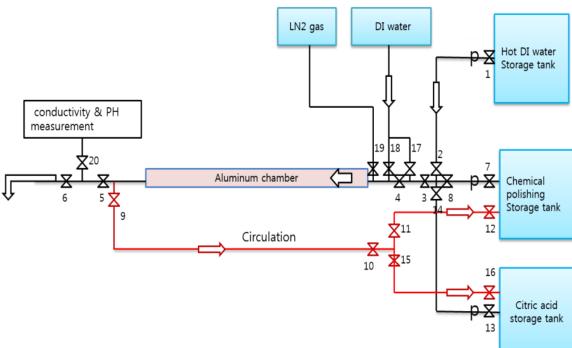


Vacuum Materials

Controlled gas

High surface quality aluminum (extruded/polished) undulator chamber









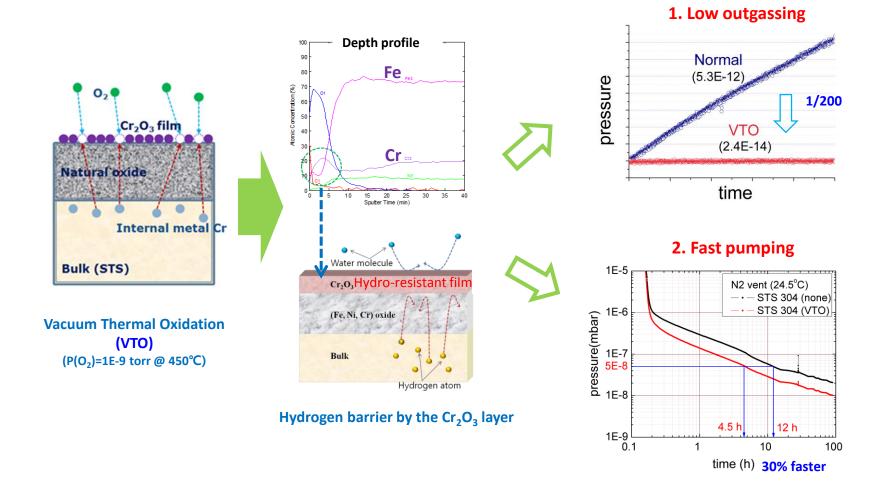
R_a < 200 nm, Oxide layer < 7 nm

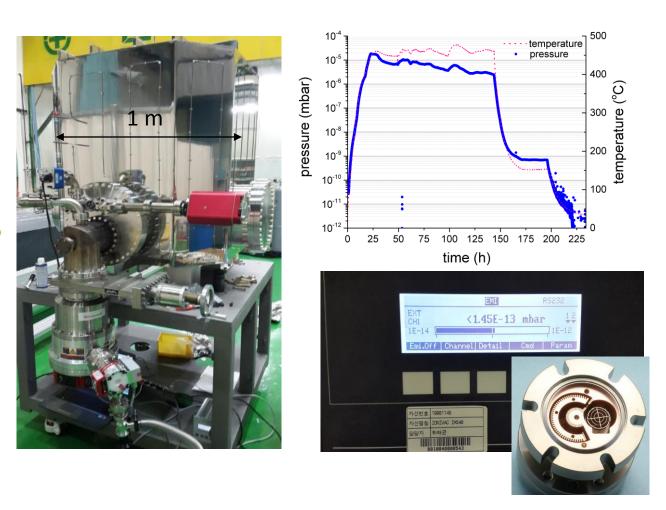
Undulator vacuum chamber for PAL-XFEL

Extrusion with controlled gas environment

Vacuum Materials

Stainless steel extreme-high vacuum (XHV) chamber





❖ Ultimate pressure < 1.4E-13 mbar!

Summary

- **Various acclerator components are developed in PAL**
 - Magnets, IVU, modulator, MPS, CCPS, RF window, SLED, accelerating column, klystron, long undulator,...
- Vacuum R&D activities in PAL
 - 4GSR vacuum chamber with function of distributed pumping and photon absorption
 - 3D printed getters and sputter ion pumps → Need optimization and more study
 - Material treatments to improve vacuum/mechanical properties
 - ✓ Cold forged oxygen free copper → High heat load vacuum components
 - ✓ High surface quality aluminum → High quality surface but easy to fabricate
 - ✓ Stainless steel for XHV → Photo-cathode gun vacuum system
- ***** Future collaboration in various fields will be beneficial to both PAL and EIC

Thank you for your attention!

